

Integrated chip package structure using silicon substrate and method of manufacturing the same

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

5 **RESPONSE TO FINAL OFFICE ACTION AND ADVISORY OFFICE
ACTION**

Sir:

In response to the Final Office Action mailed Dec. 10, 2008 and Advisory Office Action mailed Mar. 26, 2009, please amend the above-identified application and consider the remarks as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 9 of this paper.